

Professional Limited Liability Company 400 Seventh Street, N.W. Washington, D.C. 20004-2218 (202) 638-6666 (202) 393-5350/51/52 (fax) www.jhip.com Firm e-mail: ip@jhip.com



YOON S. HAM Direct: (202) 662-8483 yham@jhip.com

July 7, 2003

Honorable Commissioner for Patents

D Box 1450,

Alexandria, VA 22313

Atty. Docket No.: <u>P68965US0</u> CUSTOMER NUMBER: 00136

Sir:

Transmitted herewith for filing is the patent application in the names of:

Sung-Kwon LEE of Ichon-shi, Republic of Korea,

for METHOD FOR FABRICATING SEMICONDUCTOR DEVICE CAPABLE OF IMPROVING GAP-FILL PROPERTY. The application comprises a  $\underline{14}$ -page specification including  $\underline{8}$  claims (1 independent) and Abstract,  $\underline{5}$  sheets of drawings (Figs. 1-2F), and a Declaration and Power of Attorney.

Accompanying this application for filing are:

- (1) Assignment document, cover sheet and \$40.00 fee for recordation of Assignment; and
- (2) A certified copy of Korean Application No. 2002-84224, filed December 26, 2002, the priority of which is claimed under 35 U.S.C. §119.

The filing fee has been calculated as shown:

Large Entity \$ 750.00 Total Claims= $\underline{8}$ ; in excess of 20 = 0 x (\$18.00) = Total Ind. Claims= $\underline{1}$ ; in excess of 03 = 0 x (\$84.00) = TOTAL FILING FEE: \$ 750.00

A check in the amount of \$790.00, is enclosed to cover the total Filing Fee and an Assignment Recordation Fee. The Commissioner is hereby authorized to charge payment of any fees set forth in Sections 1.16 or 1.17 during the pendency of this application, or credit any overpayment, to deposit Account No. 06-1358. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

*!* :

Yoon S. Ham, Req. No. 45,307

YSH: kyc Enclosures